



## **SPECIFICATION**

• Supplier : Samsung electro-mechanics • Samsung P/N : CL10B104KO8NNWC

• Product : Multi-layer Ceramic Capacitor • Description : CAP, 100 nF, 16V, ±10%, X7R, 0603

## A. Samsung Part Number

<u>CL</u> <u>10</u> <u>B</u> <u>104</u> <u>K</u> <u>O</u> <u>8</u> <u>N</u> <u>N</u> <u>W</u> <u>C</u> ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

① Seri	i <b>es</b> Samsunç	Samsung Multi-layer Ceramic Capacitor						
② Size	0603 (	(inch code) L:	1.6	± 0.1	mm	W:	$0.8 \pm 0.1$	mm
③ Diel	ectric X7R		8	Inner ele	ectrode	N	İ	
4 Cap	<b>acitance</b> 100 n	nF		Termina	tion	С	u	
⑤ Сар	pacitance ±10 %	%		Plating		S	n 100%	(Pb Free)
tole	rance		9	Product		N	ormal	
6 Rate	ed Voltage 16 \	V	10	Special		P	roduct for N	etwork application
7 Thio	ckness 0.8 ±	± 0.1 mm	11)	Packagi	ng	С	ardboard Ty	ype, 7" reel

## **B. Samsung Reliability Test and Judgement condition**

	Performance	Test condition				
Capacitance	Within specified tolerance	1kHz±10% 1.0±0.2Vrms				
Tan δ (DF)	0.035 max.					
Insulation	10,000Mohm or 100Mohm⋅µF	Rated Voltage 60~120 sec.				
Resistance	Whichever is Smaller					
Appearance	No abnormal exterior appearance	Microscope (×10)				
Withstanding	No dielectric breakdown or	250% of the rated voltage				
Voltage	mechanical breakdown					
Temperature	X7R					
Characteristics	(From -55℃ to 125℃, Capacitance change should be within ±15%)					
Adhesive Strength	No peeling shall be occur on the	500g·F, for 10±1 sec.				
of Termination	terminal electrode					
Bending Strength	Capacitance change : within ±12.5%	Bending to the limit (1mm)				
		with 1.0mm/sec.				
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder				
	is to be soldered newly	245±5°C, 3±0.3sec.				
		(preheating : 80~120 ℃ for 10~30sec.)				
Resistance to	Capacitance change: within ±7.5%	Solder pot : 270±5°C, 10±1sec.				
Soldering heat	Tan δ, IR : initial spec.					

	Performance	Test condition			
Vibration Test	Capacitance change : within ±5%	Amplitude : 1.5mm			
	Tan δ, IR : initial spec.	From 10Hz to 55Hz (return : 1min.)			
		2hours × 3 direction (x, y, z)			
Moisture	Capacitance change: within ±12.5%	With rated voltage			
Resistance	Tan δ : 0.05 max	40±2℃, 90~95%RH, 500+12/-0hrs			
	IR: 500Mohm or 25Mohm · μF				
	Whichever is Smaller				
High Temperature	Capacitance change: within ±12.5%	With 200% of the rated voltage			
Resistance	Tan δ : 0.05 max	Max. operating temperature			
	IR: 1000Mohm or 50Mohm $\cdot \mu$ F				
	Whichever is Smaller	1000+48/-0hrs			
Temperature	Capacitance change : within ±7.5%	1 cycle condition			
Cycling	Tan δ, IR : initial spec.	Min. operating temperature → 25°C			
		→ Max. operating temperature → 25°C			
		5 cycle test			

## C. Recommended Soldering method :

Reflow ( Reflow Peak Temperature : 260+0/-5  $^{\circ}$ C , 10sec. Max )

<sup>\*</sup> For the more detail Specification, Please refer to the Samsung MLCC catalogue.